

LIST OF DOCUMENTS CITED BY APPLICANT
(Use several sheets if necessary)ATTY. DOCKET NO.
01 P 7422 US 01SERIAL NO.
TBD11031 U.S. PTO
09/05/14/01
09/05/14/01
11031 U.S. PTO
09/05/14/01
11031 U.S. PTO
09/05/14/01APPLICANT
Xian J. NingFILING DATE
May 14, 2001GROUP
TBD

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							VIS	SO
	AL							
	AM							
	AN							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

LV	AO	Chi-Tzung Wang, et al., Pad Wear Analysis in CMP; 1999 VMIC Conference; 1999 IMIC 109/99/0267(c)
LV	AP	Sriji Raghavan, et al., Electrochemical Behavior of Copper and Tantalum in Silica Slurries Containing Hydroxylamine, 1999 VMIC Conference; 1999 IMIC 109/99/0619(c)
LV	AQ	Rajeev Bajaj, et al., Manufacturability Considerations and Approaches for Development of a Copper CMP Process; 1999 VMIC Conference; 1999 IMIC 109/99/0144(c)

A copy of this document is maintained in the Office of the Commissioner of Patents and Trademarks. It is the property of the U.S. Patent and Trademark Office and may not be reproduced without the express written consent of the Commissioner.

DATE CONSIDERED: 12/4/2003

EXAMINER: LAN VINH

